

Cross section of CMOS7SF Technology (3 levels of metal, wirebond option) DV post etch

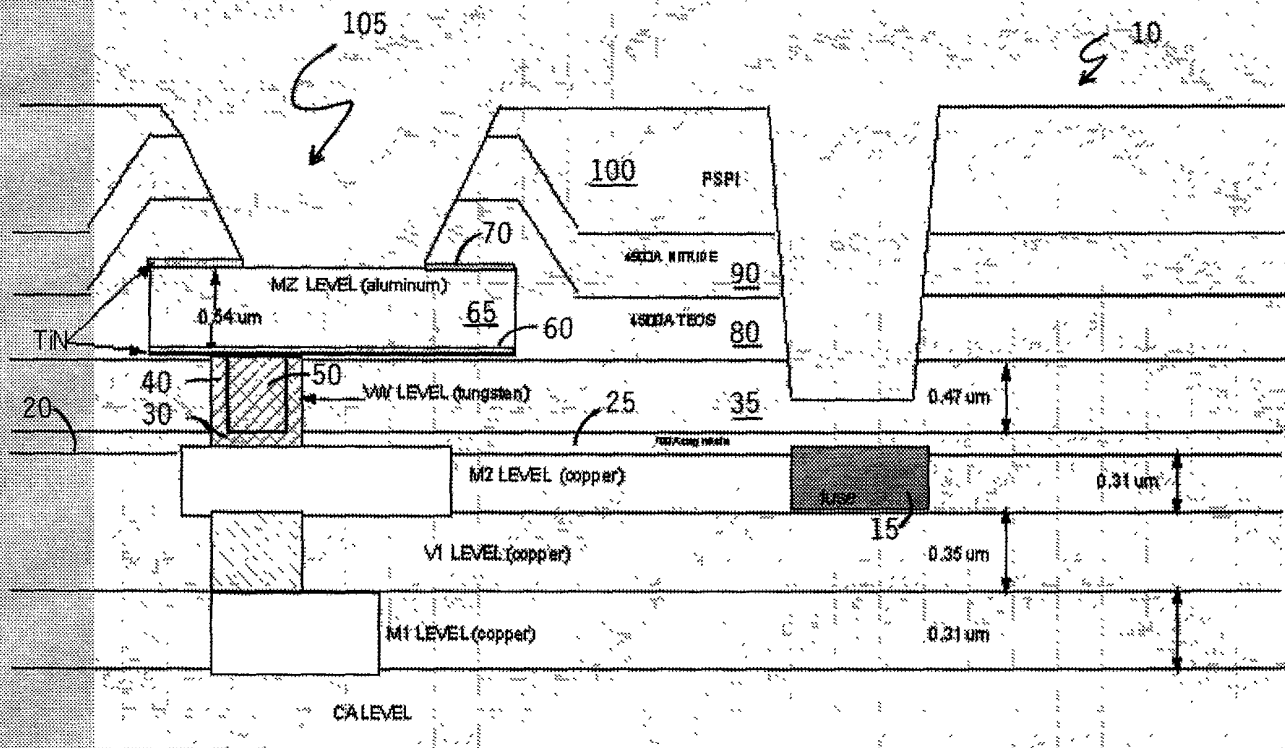


FIGURE 1

Cross section of CMOS7SF Technology 3 levels of metal, using W via and aluminum last metal

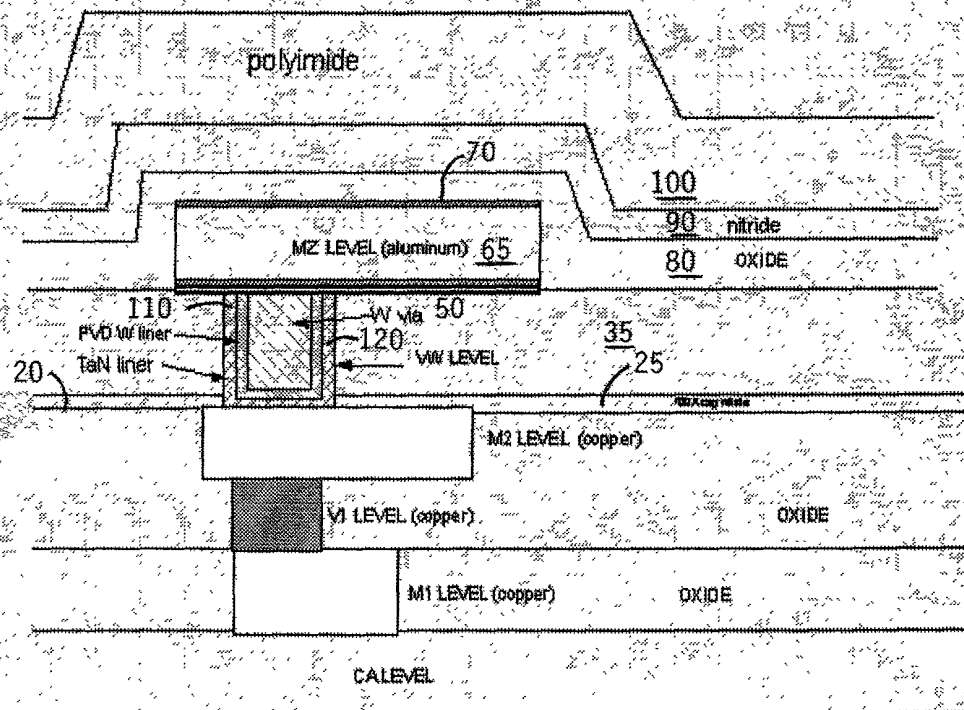


FIGURE 2